

Company – Navitas Semiconductor, Inc.

Title: Power Modules Engineer

Reports to: Sr. Package Engineering Manager

Job purpose:

Navitas is looking for a self-driven individual with background in power electronics and system. By leveraging Navitas proprietary GaN technology, products with innovative packaging, and design expertise to lead the definition, design, and product development to volume production of power module products. The role is hands-on and requires collaborations with cross-functional teams (NPI, Test, Applications, Marketing). The role is expected to have a solid understanding of the design parameters and perform design analysis/feasibility that involves simulation, evaluation, characterization and validation to meet performance, reliability, manufacturing/test and cost to meet design requirements and targets.

Key Responsibilities and Accountabilities:

1. Work with subcontractors on characterizing assembly processes and monitoring execution
2. Use Project management tool to manage NPI subcon activities from process characterization to assembling Qualification lots
3. Generate and update Design Rule Specification related to Power Module by working with different subcontractors.
4. Manage and prevent risks in running NPI products in assembly.
5. Support investigation and resolution of quality, yield and customer return issue
6. Technical lead role for multi-chip module (MCM) based product development.
7. Advanced package design skill using 2.5D and 3D CAD drawing software
8. Support product through critical lifecycle stages including concept/feasibility, development, qualification, and production

Background and Expertise:

1. Bachelor's or Master's Degree in Electrical Engineering
2. Have at least 10 years' experience working for Semiconductor company; with hands-on experience on Power Modules Design and assembly processes.
3. Strong track records in system/power module design
4. Ability to thrive in an extremely fast-paced, start-up environment.
5. Relevant experience in multi-chip module (MCM) design
6. Broad knowledge of semiconductor power packaging, materials and assembly processes
7. Good aptitude and skill in using Project Management software
8. Ability to work positively with the wide range of individuals involved in the program management
9. Experienced using AutoCAD; 2D and 3D, and preferably skills in doing Thermal /Mechanical simulations
10. Exceptional ability to find innovative ways to resolve conflicts and problems
11. Good English written and verbal communication skills